FINAL PRODUCT/PROCESS CHANGE NOTIFICATION #20637

Generic Copy

Issue Date: 13-Jan-2015

TITLE: Additional Assembly manufacture site for LE25U40CMCSxx & LE25U40CMCQxx series

PROPOSED FIRST SHIP DATE: 20-Apr-2015

AFFECTED CHANGE CATEGORY(S): Product assembly site addition

FOR ANY QUESTIONS CONCERNING THIS NOTIFICATION:
Contact your local ON Semiconductor Sales Office or
< Ai-Ling.Loh@Onsemi.com> or < Karl.Hill@onsemi.com>

SAMPLES: Contact your local ON Semiconductor Sales Office or
<Jun.Hasunuma@onsemi.com>

ADDITIONAL RELIABILITY DATA: Available
Contact your local ON Semiconductor Sales Office or <Kazutoshi.Kitazume@onsemi.com>

NOTIFICATION TYPE:

Final Product/Process Change Notification (FPCN)

Final change notification sent to customers. FPCNs are issued at least 90 days prior to implementation of the change.

ON Semiconductor will consider this change approved unless specific conditions of acceptance are provided in writing within 30 days of receipt of this notice. To do so, contact <quality@onsemi.com>.

DESCRIPTION AND PURPOSE:

This change is addition of the back-end manufacturing site for LE25U40CMC series produced in Amkor Philippines. The addition of this production factory enables stable timely product supply.

There is no characteristic change to use same DIE. Assembly and testing site change from Amkor Philippines to ON Semiconductor Philippines. Inc. (OSPI).

OSPI has actual production of the flash memory using the similar package. Package materials except mold resin are changed. But OSPI have the experience of the material in other flash memory. Therefore there is no risk by this change.

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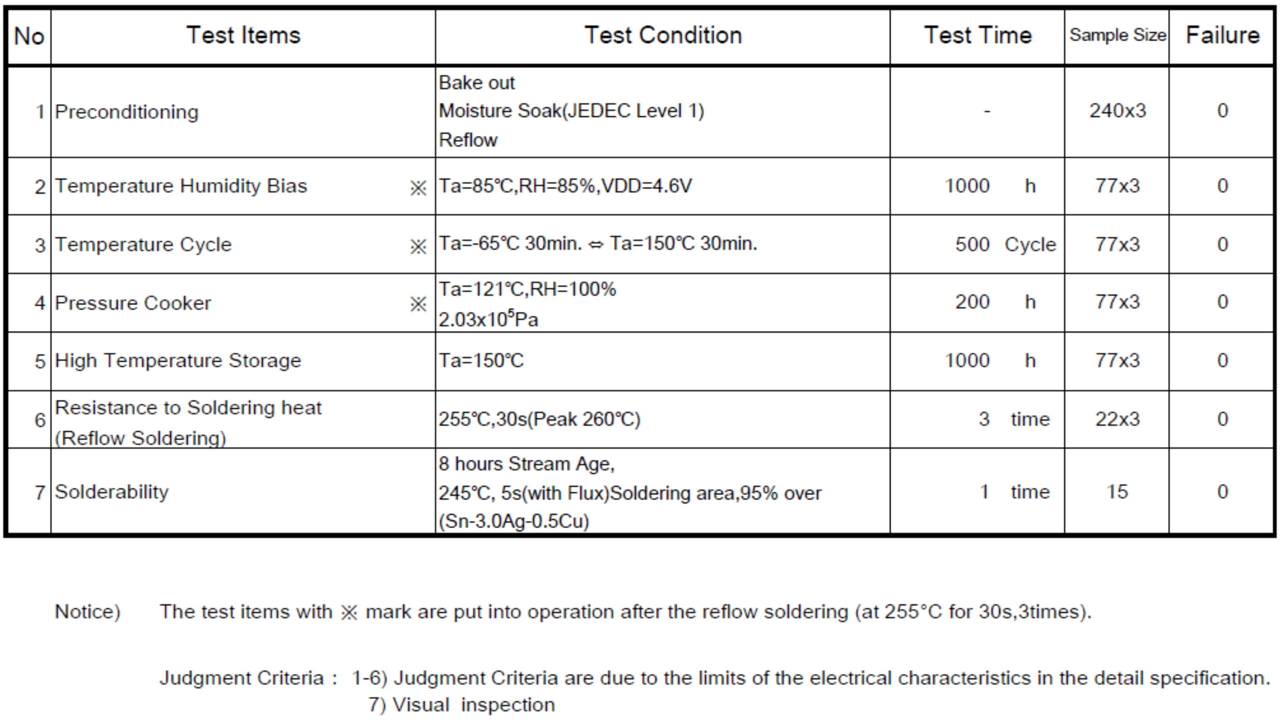
RELIABILITY DATA SUMMARY:

Reliability Test Results:



No	Test Items		Test Condition	Test Time	Sample Size	Failure
1	Preconditioning		Bake out Moisture Soak(JEDEC Level 1) Reflow	-	240x3	0
2	Temperature Humidity Bias	※	Ta=85℃,RH=85%,VDD=4.6V	1000 h	77x3	0
3	Temperature Cycle	※	Ta=-65℃ 30min. ⇔ Ta=150℃ 30min.	500 Cycle	77x3	0
4	Pressure Cooker	※	Ta=121℃,RH=100% 2.03x10^5Pa	200 h	77x3	0
5	High Temperature Storage		Ta=150℃	1000 h	77x3	0
6	Resistance to Soldering heat (Reflow Soldering)		255℃,30s(Peak 260℃)	3 time	22x3	0
7	Solderability		8 hours Stream Age, 245℃, 5s(with Flux)Soldering area,95% over (Sn-3.0Ag-0.5Cu)	1 time	15	0

Notice) The test items with ※ mark are put into operation after the reflow soldering (at 255°C for 30s,3times).

Judgment Criteria : 1-6) Judgment Criteria are due to the limits of the electrical characteristics in the detail specification.
7) Visual inspection

ELECTRICAL CHARACTERISTIC SUMMARY:

Electrical characterization is not impacted because DIE does not change.

CHANGED PART IDENTIFICATION:

Orderable part name, OPN, is different and 1-pin index mark of top marking is also different.
Please refer to the attached FPCN appendix.

To access file attachments on pdf copy of PCN, please be guided by the steps below:

1. *Download pdf copy of the PCN to your computer*
2. *Open the downloaded pdf copy of the PCN*
3. *Click on the paper clip icon available on the menu provided in the left/bottom portion of the screen to reveal the Attachment field*
4. *Then click on the attached file/s*

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List of Affected Customer Specific Parts:

LE25U40CMCQ00-AH
LE25U40CMCQ05-AH
LE25U40CMCQ07-AH
LE25U40CMCQ08-AH
LE25U40CMCQ09-AH
LE25U40CMCS00-AH
LE25U40CMCS01-AH
LE25U40CMCS02-AH